

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

HIDEYUKI ARAKAWA

Application No. Unassigned Art Unit: Unassigned

Filed: August 23, 2001 Examiner: Unassigned

For: SEMICONDUCTOR
DEVICE AND
MANUFACTURING
METHOD THEREOF

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D. C. 20231

Dear Sir:

Prior to the examination of the above-identified patent application, please enter the following amendments and consider the following remarks.

IN THE SPECIFICATION:

Replace the paragraph beginning at page 1, line 20, with:

When a reverse loop such as shown in Fig. 8 is utilized, an inner lead 10 and a bonding pad 6 are connected by means of a first ball 2, a bonding wire 1, and a stud bump (second ball) 9. Bonding pad 6 is formed on a semiconductor device (chip) 7 mounted on a die pad 8.